

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
- 2. ASSEMBLY PROCESS: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEG. C.
- 3. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
- 4. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.

VERSION	U1	L1, L4	L2, L3
-A	LTC3644	XFL4020-222ME	XFL4020-472ME
-B	LTC3644-2	DFE252012F-1R0M	DFE252012F-2R2M

